

Description

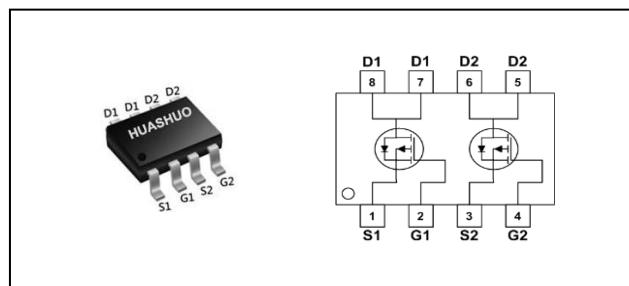
The HSM4963 is the high cell density trenched P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The HSM4963 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Product Summary

V_{DS}	-20	V
$R_{DS(ON),typ}$	40	$m\Omega$
I_D	-6	A

SOP8 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-20	V
V_{GS}	Gate-Source Voltage	± 12	V
$I_D @ T_A=25^\circ C$	Continuous Drain Current, $-V_{GS} @ -10V^1$	-6	A
$I_D @ T_A=70^\circ C$	Continuous Drain Current, $-V_{GS} @ -10V^1$	-5	A
I_{DM}	Pulsed Drain Current ²	-24	A
$P_D @ T_A=25^\circ C$	Total Power Dissipation ⁴	2	W
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	---	110	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	50	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu\text{A}$	-20	---	---	V
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance ²	$V_{GS}=-4.5V, I_D=-6A$	---	40	55	$\text{m}\Omega$
		$V_{GS}=-2.5V, I_D=-5A$	---	50	65	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D = -250\mu\text{A}$	-0.5	-0.85	-1.2	V
$\Delta V_{GS(\text{th})}$	$V_{GS(\text{th})}$ Temperature Coefficient		---	4.6	---	$\text{mV}/^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=-20V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	-1	uA
		$V_{DS}=-20V, V_{GS}=0V, T_J=55^\circ\text{C}$	---	---	-5	
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 12V, V_{DS}=0V$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{DS}=-5V, I_D=-4A$	---	5	---	S
Q_g	Total Gate Charge (-4.5V)	$V_{DS}=-10V, V_{GS}=-4.5V, I_D=-4A$	---	8	---	nC
Q_{gs}	Gate-Source Charge		---	2	---	
Q_{gd}	Gate-Drain Charge		---	3	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=-10V, V_{GS}=-4.5V, R_L=9.1\Omega, I_D=-6A, R_{GEN}=1\Omega$	---	12	---	ns
T_r	Rise Time		---	36	---	
$T_{d(off)}$	Turn-Off Delay Time		---	30	---	
T_f	Fall Time		---	10	---	
C_{iss}	Input Capacitance	$V_{DS}=-10V, V_{GS}=0V, f=1\text{MHz}$	---	740	---	pF
C_{oss}	Output Capacitance		---	275	---	
C_{rss}	Reverse Transfer Capacitance		---	195	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V_{SD}	Diode Forward Voltage ²	$V_{GS}=0V, I_S=-1A, T_J=25^\circ\text{C}$	---	---	-1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The power dissipation is limited by 150°C junction temperature
- 4.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.



Dual P-Ch 30V Fast Switching MOSFETs

Typical Characteristics

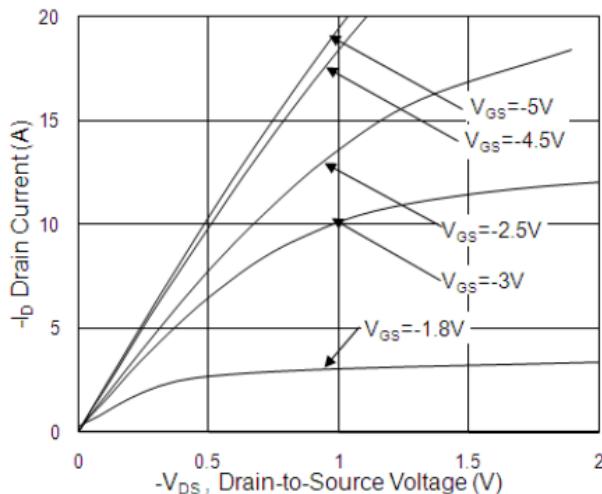


Fig.1 Typical Output Characteristics

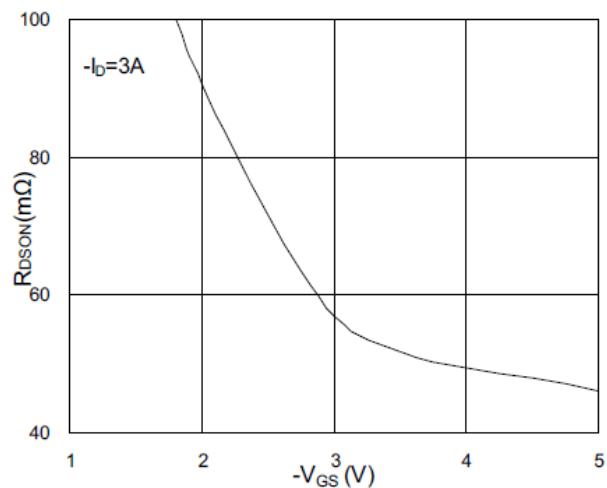


Fig.2 On-Resistance vs. G-S Voltage

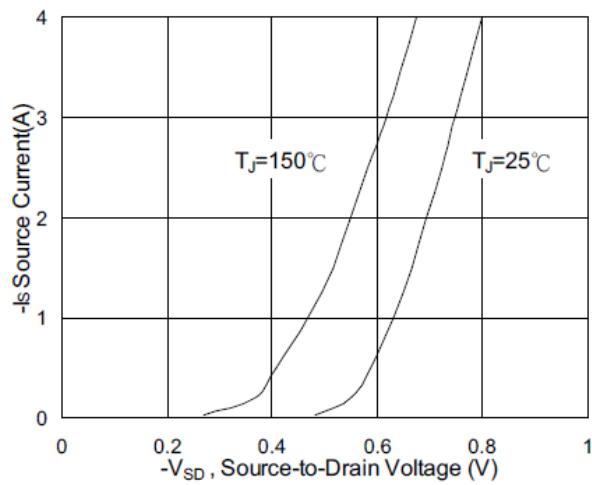


Fig.3 Forward Characteristics of Reverse

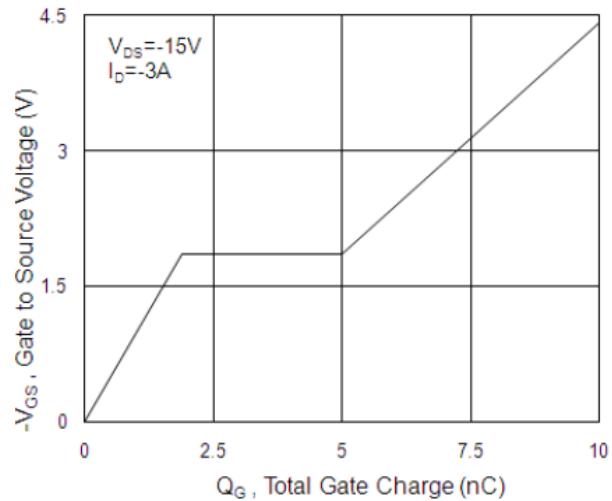


Fig.4 Gate-charge Characteristics

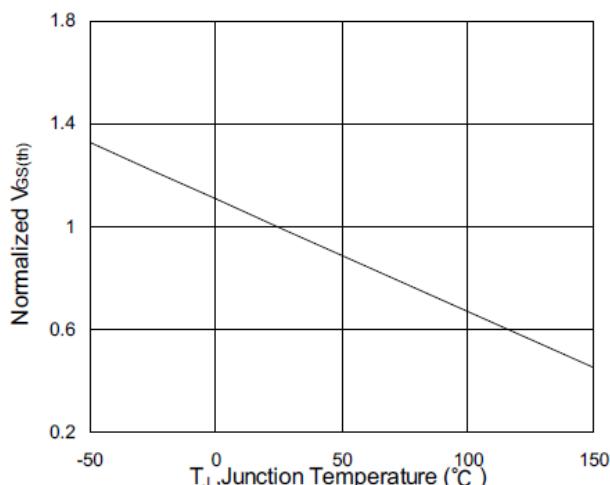


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

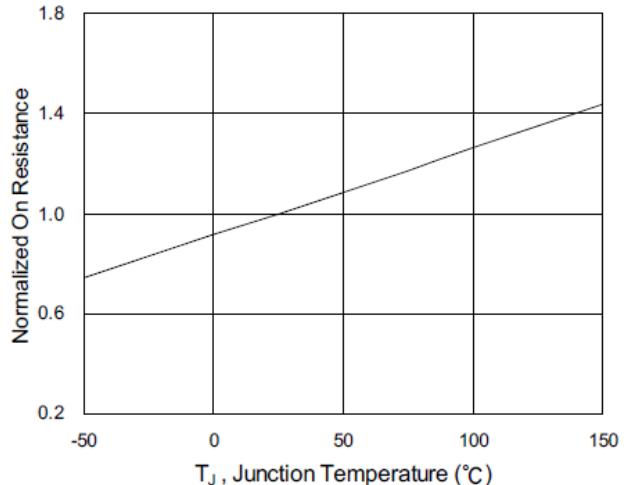


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

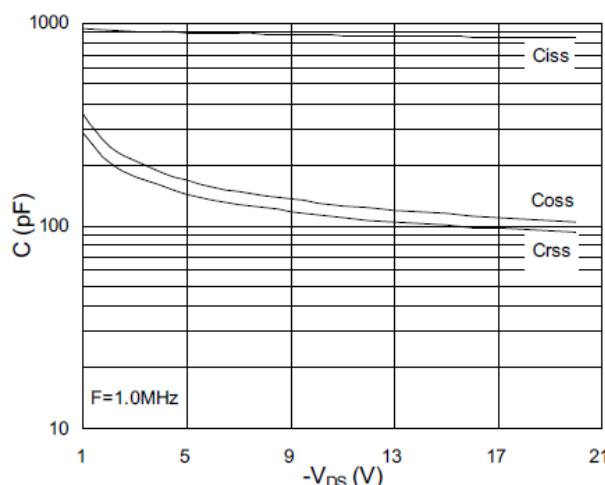


Fig.7 Capacitance

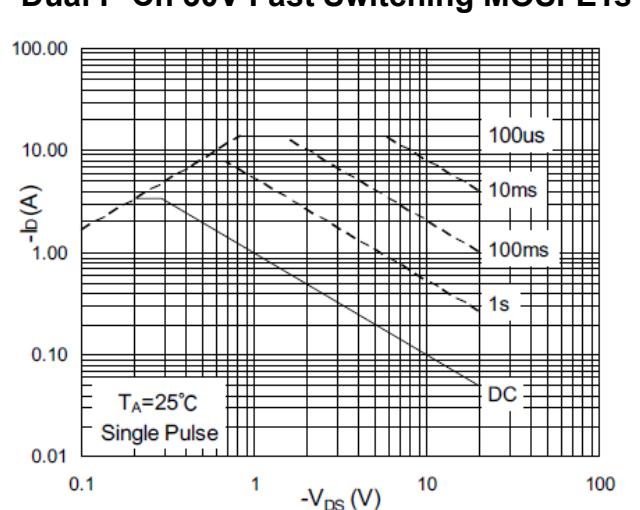


Fig.8 Safe Operating Area

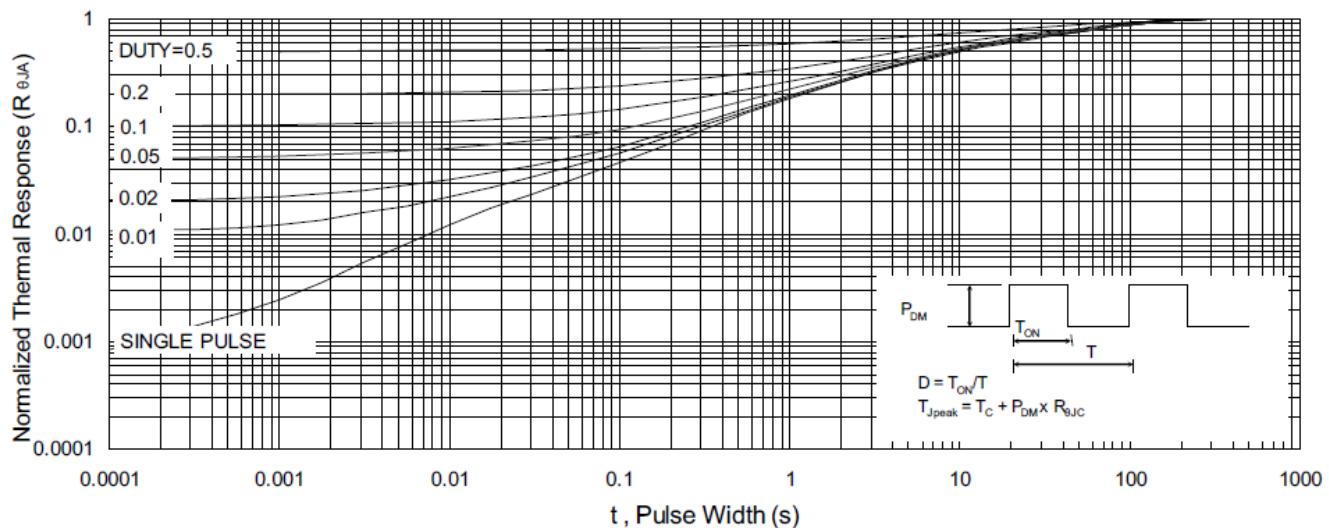


Fig.9 Normalized Maximum Transient Thermal Impedance

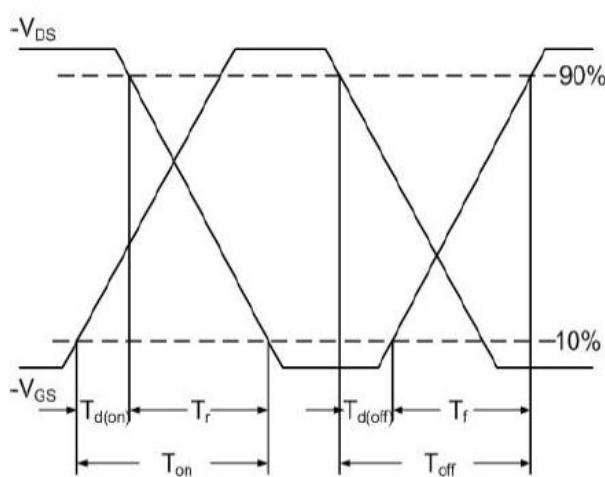


Fig.10 Switching Time Waveform

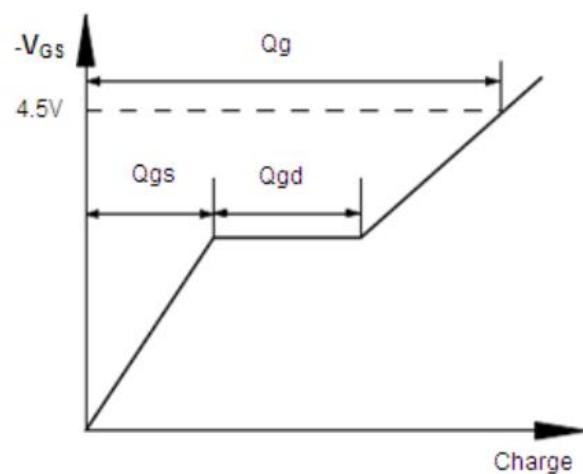


Fig.11 Gate Charge Waveform



Ordering Information

Part Number	Package code	Packaging
HSM4963	SOP-8	4000/Tape&Reel

